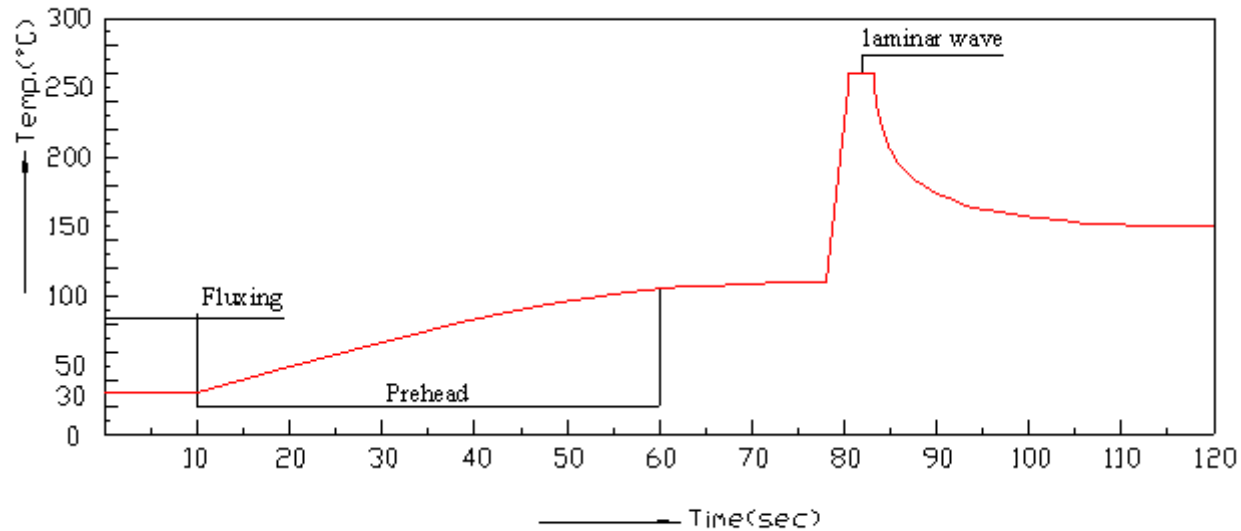


Through-hole Display 使用説明

Wave Soldering(Not include soldering iron)

RDSMD
2017.2

Soldering Condition



Preheat

Temperature 100 °C
Time 60 seconds max.

Other

Bath Temperature 260 °C
Bath Time 5 seconds max.
DIP Soldering 1 time

All parameters are maximum body case temperature values and cannot be considered as a soldering profile. The body case temperature was measured by soldering a thermal couple to the soldering point of LEDs.

Soldering Instructions

- 禁止在高溫下加工。

Processing under high temperature is forbidden.

- 建議客戶在經波峰焊後加裝風扇，以利散熱，需等LED冷卻後（最好為室溫後），再進行下一工序加工。

It is recommended to install a fan in the exit of the wave solder machine to cool down the temperature. Wait until the LED fully cooled down(Better to be room temperature), then to the next process

Soldering Instructions

- 焊錫位置距膠體/反射蓋距離最小為3mm

Leave at least 3mm between **epoxy/reflector** and solder position.

- 禁止使用於迴流焊

Reflow soldering is NOT available.

- 避免在高溫下碰觸其膠體與PIN腳，以防止應力拉扯斷第二焊點。

Avoid touching epoxy and PIN under high temperature to prevent the second welding point being stressed to crack